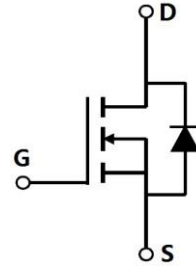


100V N-SGT Enhancement Mode MOSFET

General Description

12N10D use advanced SGT MOSFET technology to provide low $R_{DS(on)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is specially designed to get better ruggedness and suitable to use in Synchronous-rectification applications.



Features

- Low $R_{DS(on)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Fast switching and soft recovery
- Invertors
- Synchronous-rectification applications

Applications

- Consumer electronic power supply
- Motor control
- Synchronous-rectification
- Isolated DC
- Synchronous-rectification applications

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
12N10D	TO-252	12N10D	2500

Absolute Maximum Ratings at $T_j=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V _{DS}	100	V
Gate source voltage	V _{GS}	±20	V
Continuous drain current ¹⁾ , $T_C=25^{\circ}\text{C}$	I _D	12	A
Pulsed drain current ²⁾ , $T_C=25^{\circ}\text{C}$	I _{D, pulse}	21	A
Power dissipation ³⁾ , $T_C=25^{\circ}\text{C}$	P _D	17	W
Single pulsed avalanche energy ⁵⁾	EAS	1.2	mJ
Operation and storage temperature	T _{stg} , T _j	-55 to 150	°C

100V N-SGT Enhancement Mode MOSFET

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	7.4	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^{\circ}\text{C}/\text{W}$

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	100			V	$V_{GS}=0\text{ V}, I_D=250\ \mu\text{A}$
Gate threshold voltage	$V_{GS(th)}$	1.5		2.5	V	$V_{DS}=V_{GS}, I_D=250\ \mu\text{A}$
Drain-source on-state resistance	$R_{DS(ON)}$		110	140	m Ω	$V_{GS}=10\text{ V}, I_D=5\text{ A}$
Drain-source on-state resistance	$R_{DS(ON)}$		160	300	m Ω	$V_{GS}=4.5\text{ V}, I_D=3\text{ A}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=20\text{ V}$
				-100		$V_{GS}=-20\text{ V}$
Drain-source leakage current	I_{DSS}			1	μA	$V_{DS}=100\text{ V}, V_{GS}=0\text{ V}$
Input capacitance	C_{iss}		206.1		pF	$V_{GS}=0\text{ V}, V_{DS}=50\text{ V}, f=100\text{ kHz}$
Output capacitance	C_{oss}		28.9		pF	
Reverse transfer capacitance	C_{rss}		1.4		pF	
Turn-on delay time	$t_{d(on)}$		14.7		ns	$V_{GS}=10\text{ V}, V_{DS}=50\text{ V}, R_G=2\ \Omega, I_D=5\text{ A}$
Rise time	t_r		3.5		ns	
Turn-off delay time	$t_{d(off)}$		20.9		ns	
Fall time	t_f		2.7		ns	
Total gate charge	Q_g		4.3		nC	$I_D=5\text{ A}, V_{DS}=50\text{ V}, V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		1.5		nC	
Gate-drain charge	Q_{gd}		1.1		nC	
Gate plateau voltage	$V_{plateau}$		5.0		V	
Diode forward current	I_S			7	A	

100V N-SGT Enhancement Mode MOSFET

Pulsed source current	I_{SP}			21		$V_{GS} < V_{th}$
Diode forward voltage	V_{SD}			1.0	V	$I_S = 7\text{ A}, V_{GS} = 0\text{ V}$
Reverse recovery time	t_{rr}		32.1		ns	$I_S = 5\text{ A},$ $di/dt = 100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		39.4		nC	
Peak reverse recovery current	I_{rrm}		2.1		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a = 25\text{ }^\circ\text{C}$.
- 5) $V_{DD} = 50\text{ V}$, $R_G = 50\text{ }\Omega$, $L = 0.3\text{ mH}$, starting $T_j = 25\text{ }^\circ\text{C}$.

Electrical Characteristics Diagrams

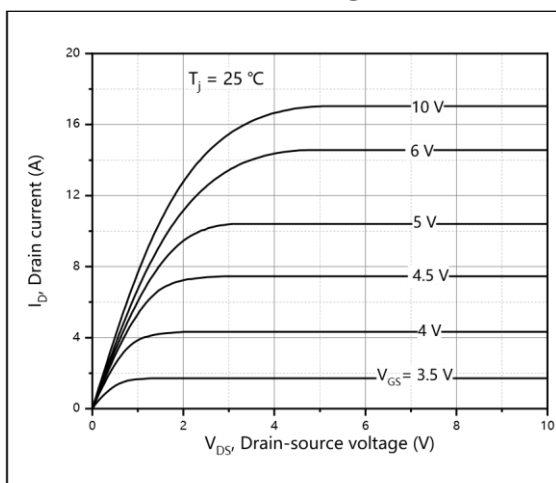


Figure 1, Typ. output characteristics

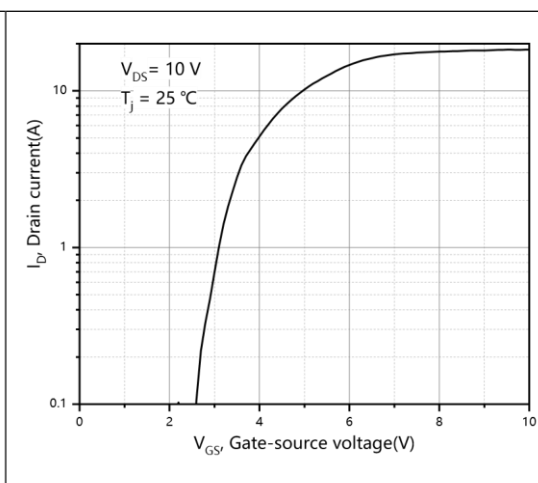


Figure 2, Typ. transfer characteristics

100V N-SGT Enhancement Mode MOSFET

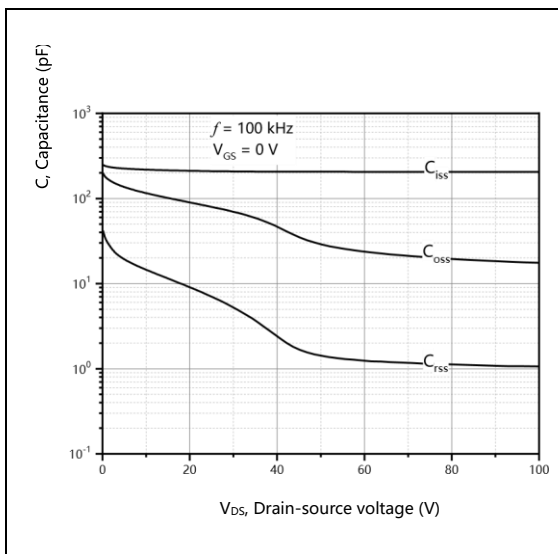


Figure 3, Typ. capacitances

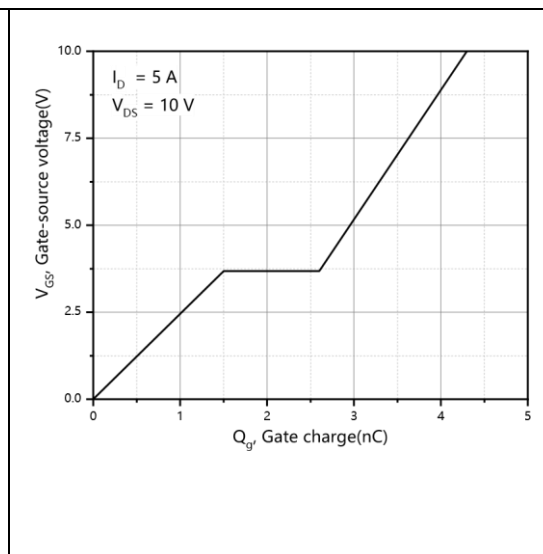


Figure 4, Typ. gate charge

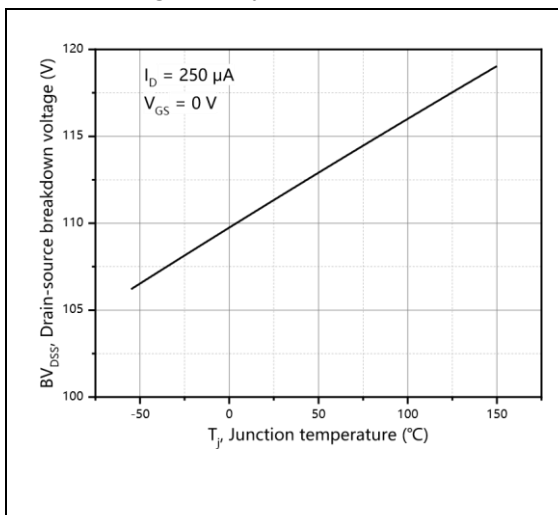


Figure 5, Drain-source breakdown voltage

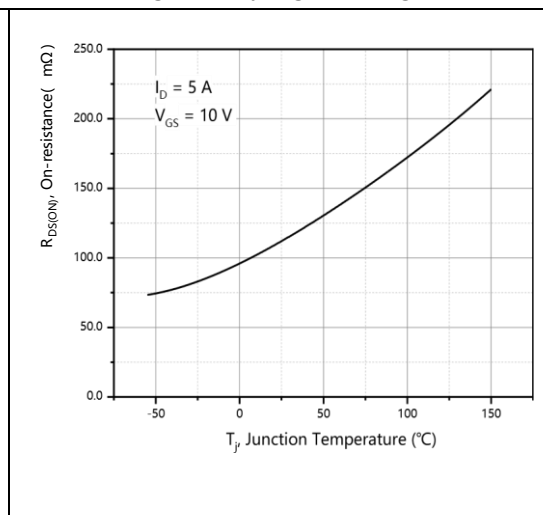


Figure 6, Drain-source on-state resistance

100V N-SGT Enhancement Mode MOSFET

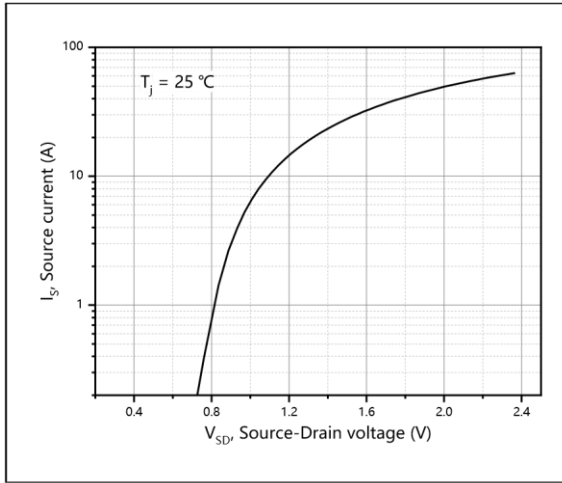


Figure 7, Forward characteristic of body diode

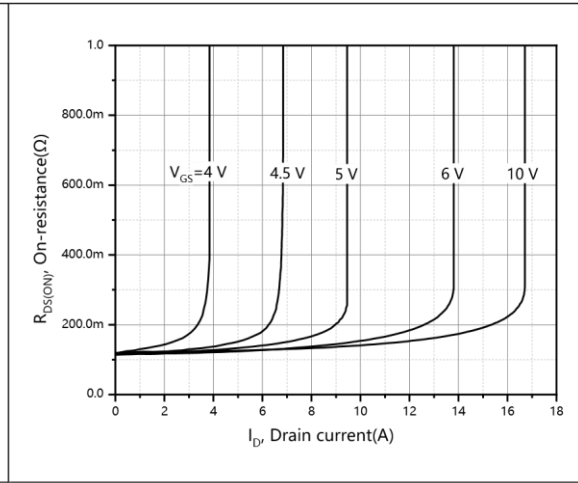


Figure 8, Drain-source on-state resistance

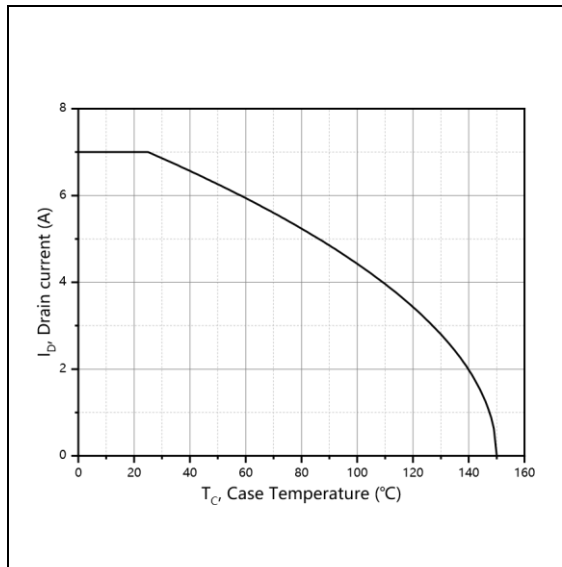


Figure 9, Drain current

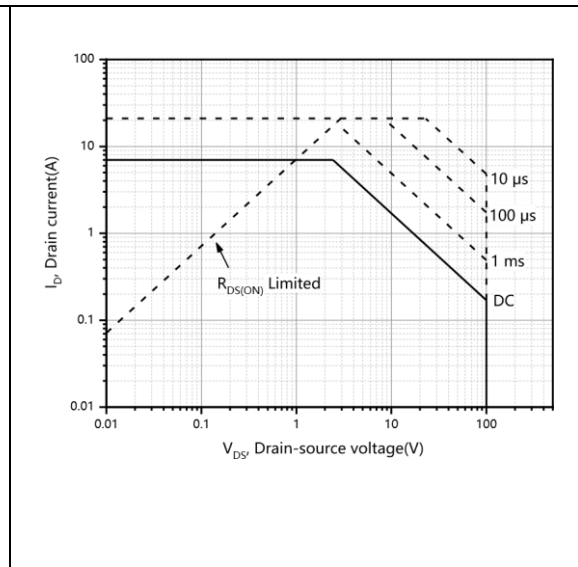


Figure 10, Safe operation area $T_C=25\text{ °C}$

100V N-SGT Enhancement Mode MOSFET

Test circuits and waveforms

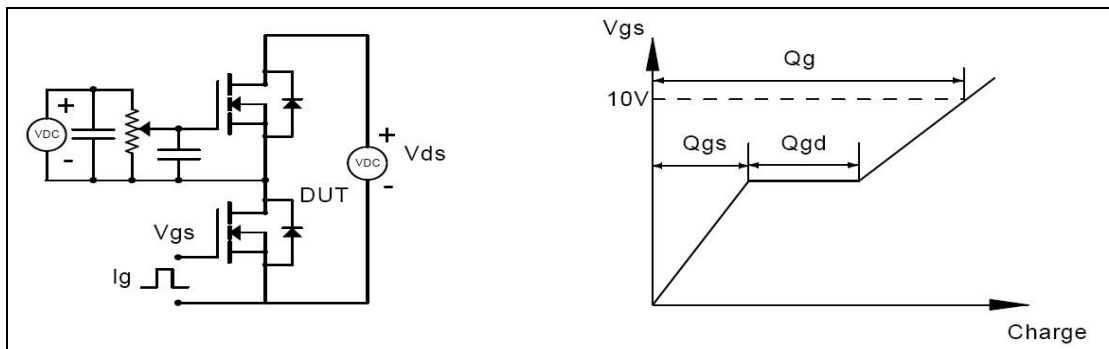


Figure 1, Gate charge test circuit & waveform

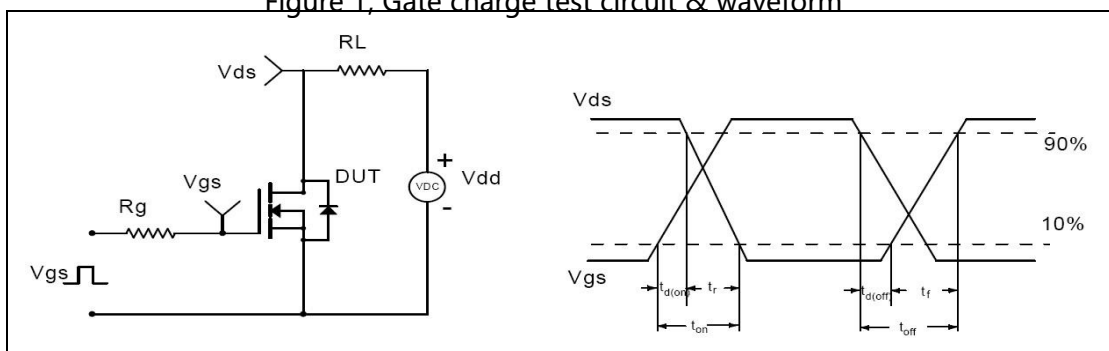


Figure 2, Switching time test circuit & waveforms

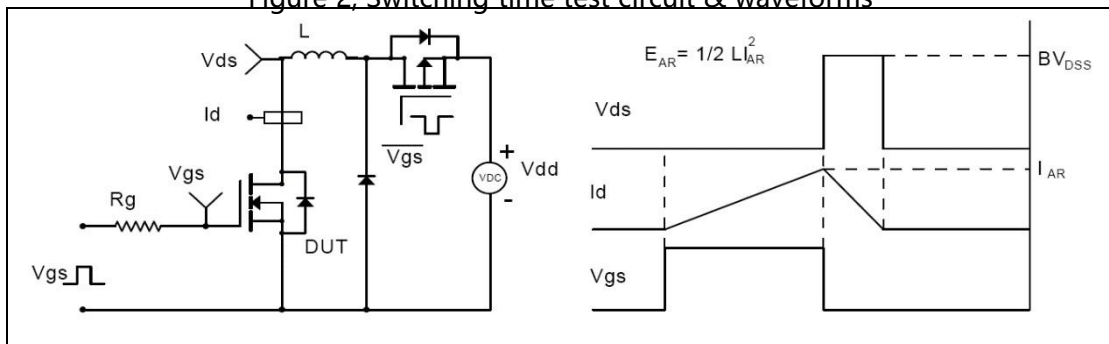


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

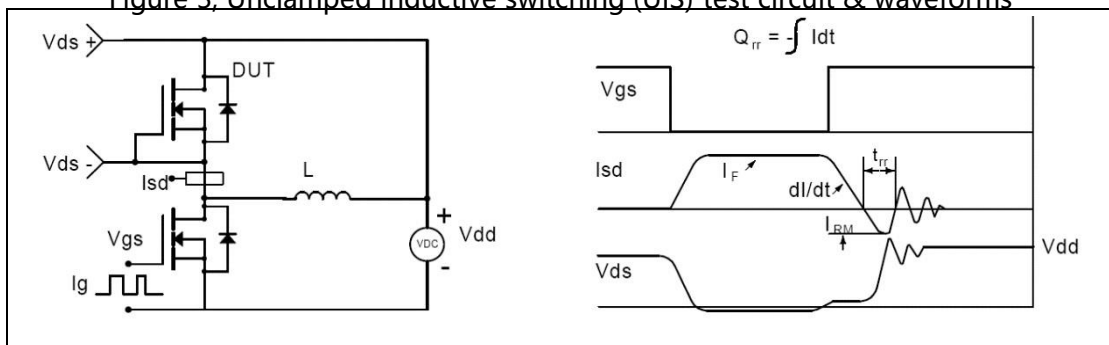
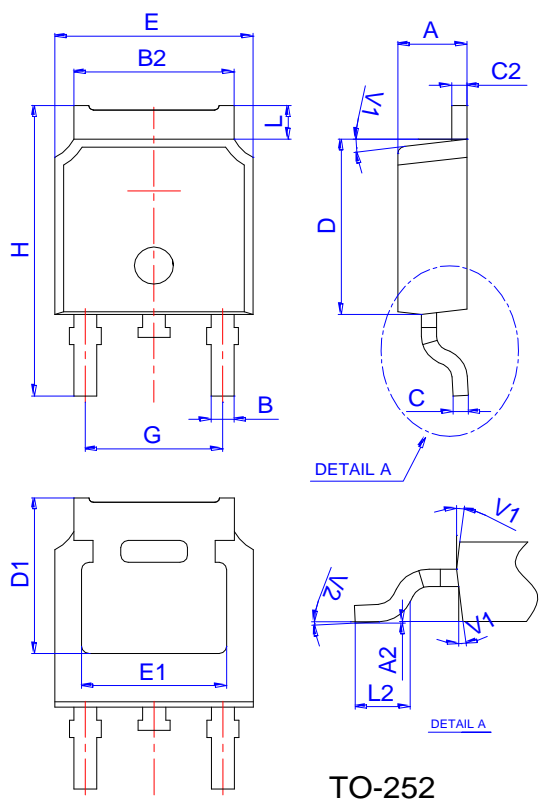


Figure 4, Diode reverse recovery test circuit & waveforms

100V N-SGT Enhancement Mode MOSFET

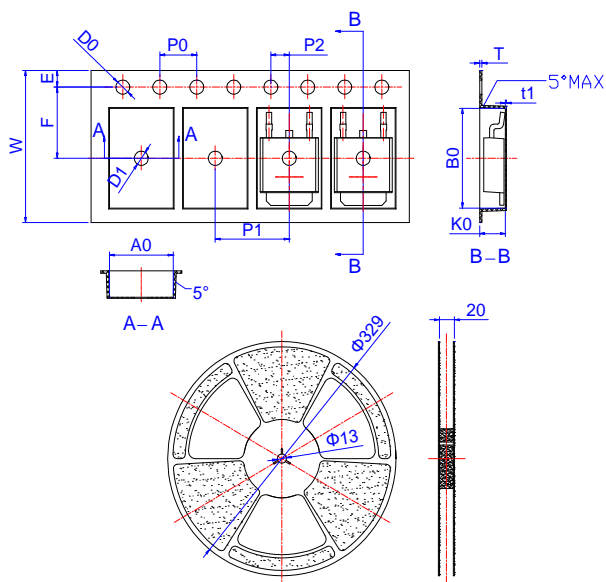
Package Mechanical Data



TO-252

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification-TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583

